

1. A device enclosure comprising:
a chassis; and
a thermo-siphon device formed as an integral part of a wall of the
chassis.

2. The device of claim 1, wherein the device is an electronic device.

3. The device of claim 2, wherein the device enclosure is a computer
chassis.

4. The device of claim 1, wherein the device is a non-electronic device.

5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.

6. The device of claim 1, wherein the thermo-siphon device is a strip of a
high efficiency conduit material.

9. The device of claim 1, wherein the wall is fabricated from a metallic
material.

10. The device of claim 1, wherein the thermo-siphon device is embedded in
a cavity of the wall.

11. The device of claim 10, wherein the cavity is created during a fabrication
process of the wall.

12. The device of claim 1, wherein the wall partially encloses the thermo-
siphon device.

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13. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

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17. The device of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the skin cavity.

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18. The device of claim 1, wherein a metallic plate interfaces a heat source with the thermo-siphon device.

19. A system comprising:
a chassis; and
a thermo-siphon device formed as an integral part of a wall of the chassis.

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20. The system of claim 19, wherein the thermo-siphon device is a heat pipe.

21. The system of claim 19, wherein the thermo-siphon device is a strip of high efficiency conduit material.

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22. The system of claim 19, wherein the housing is a computer chassis.

24. A computer chassis comprising:
a chassis; and
a thermo-siphon device formed as an integral part of a wall of the chassis.

25. ~~The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.~~

Cond AI Cont SubC1 26. ~~The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.~~

28. ~~The computer chassis of claim 27, wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.~~

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